

20V/17A N-Channel Advanced Power MOSFET

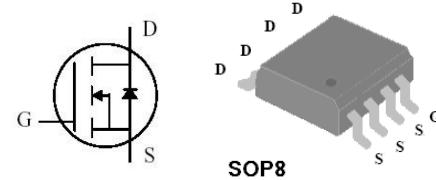
Features

- Very Low $R_{DS(on)}$ @ 3.3V Logic.
- 3.3V Logic Level Control
- SOP8 Package
- Pb-Free, RoHS Compliant

BVDSS	20	V
ID	17	A
$R_{DS(on)}$ @ $V_{GS}=4.5V$	5.5	$m\Omega$
$R_{DS(on)}$ @ $V_{GS}=3.3V$	6.5	$m\Omega$

Applications

- Low Side Load Switch
- Battery Switch
- Optimized for Power Management Applications for Portable Products, such as Aeromodelling, Power bank, Brushless motor, Main board , and Others



Order Information

Product	Package	Marking	Packing	Min Unit Quantity
PTS2017	SOP8	PTS2017	3000PCS/Reel	6000PCS

Absolute Maximum Ratings

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Symbol	Parameter	Rating	Unit	
Common Ratings ($T_c=25^\circ C$ Unless Otherwise Noted)				
V_{GS}	Gate-Source Voltage	± 8	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	20	V	
T_J	Maximum Junction Temperature	150	$^\circ C$	
T_{STG}	Storage Temperature Range	-55 to 175	$^\circ C$	
I_s	Diode Continuous Forward Current	$T_c=25^\circ C$	17	A
Mounted on Large Heat Sink				
I_{DM}	Pulse Drain Current Tested (Silicon Limit)	$T_c=25^\circ C$	68	A
I_D	Continuous Drain current@ $V_{GS}=4.5V$ (Note2)	$T_c=25^\circ C$	17	A
P_D	Maximum Power Dissipation	$T_c=25^\circ C$	2	W
$R_{\theta JA}$	Thermal Resistance Junction-to-Ambient – Steady State (Note 1)	65	$^\circ C/W$	
	Thermal Resistance Junction-to-Ambient – $t \leq 5$ s (Note 1)	80	$^\circ C/W$	

Note :

1. Surface-mounted on FR4 board using 1 in sq. pad size (Cu area = 1.127 in sq. [2 oz] including traces).

2. Pulse Test: pulse width ≤ 300 us, duty cycle $\leq 2\%$

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ $ID=250\mu\text{A}$	8	--	--	V
I_{DSS}	Zero Gate Voltage Drain current($T_c=25^\circ\text{C}$)	$V_{DS}=16\text{V}, V_{GS}=0\text{V}$	--	--	1	μA
	Zero Gate Voltage Drain Current($T_c=125^\circ\text{C}$)	$V_{DS}=16\text{V}, V_{GS}=0\text{V}$	--	--	100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 8\text{V}, V_{DS}=0\text{V}$	--	--	± 10	μA
$V_{\text{GS(TH)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, ID=250\mu\text{A}$	0.45	0.70	1.20	V
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance note A	$V_{GS}=4.5\text{V}, ID=12\text{A}$	--	5.5	7.5	$\text{m}\Omega$
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance note A	$V_{GS}=3.3\text{V}, ID=10\text{A}$	--	6.5	8	$\text{m}\Omega$
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance note A	$V_{GS}=2.5\text{V}, ID=10\text{A}$	--	7.5	9	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated) note B						
C_{iss}	Input Capacitance	$V_{DS}=5\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	--	1550	--	pF
C_{oss}	Output Capacitance		--	140	--	pF
C_{rss}	Reverse Transfer Capacitance		--	105	--	pF
Q_g	Total Gate Charge $V_{GS}=-4.5\text{V}$	$V_{DS}=5\text{V}, ID=10\text{A}, V_{GS}=4.5\text{V}$	--	58	--	nC
			--	25	--	nC
Q_{gs}	Gate-Source Charge		--	18	--	nC
Q_{gd}	Gate-Drain Charge		--	12	--	nC
Switching Characteristics note B						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{DD}=10\text{V}, ID=3\text{A}, RG=4.7\Omega, V_{GS}=4.5\text{V}$	--	20	--	nS
t_r	Turn-on Rise Time		--	12	--	nS
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	25	--	nS
t_f	Turn-Off Fall Time		--	18	--	nS
Source- Drain Diode Characteristics@ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
I_{SD}	Source-drain current(Body Diode)	$T_c=25^\circ\text{C}$	--	--	20	A
V_{SD}	Forward on voltage	$IS=10\text{A}, V_{GS}=0\text{V}$	--	0.8	1.2	V
t_{rr}	Reverse Recovery Time	$T_j=25^\circ\text{C}, ISD=1\text{A}, V_{GS}=0\text{V}$ $dI/dt=100\text{A}/\mu\text{s}$	--	2	--	nS
Q_{rr}	Reverse Recovery Charge		--	5	--	nC

Note:

A: Pulse Test: pulse width $\leq 300\text{ us}$, duty cycle $\leq 2\%$

B:Guaranteed by design, not subject to production testing.

Typical Characteristics

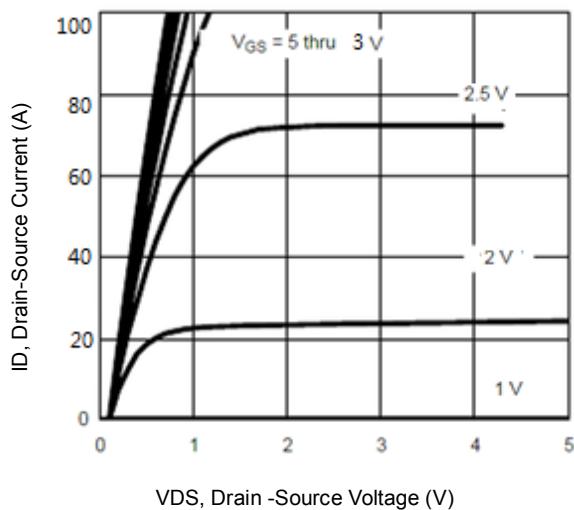


Fig1. Typical Output Characteristics

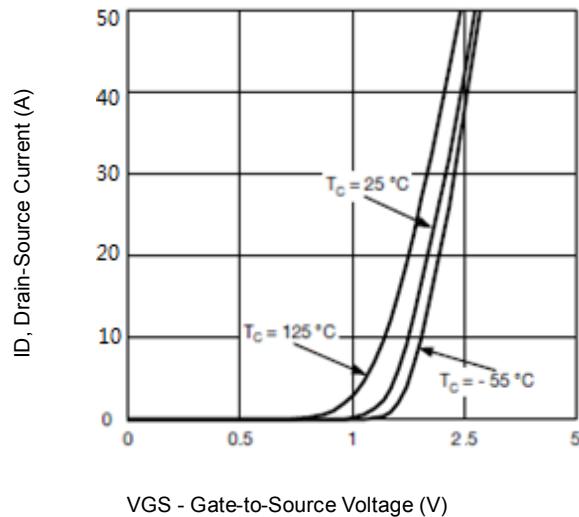


Fig2. Transfer Characteristics

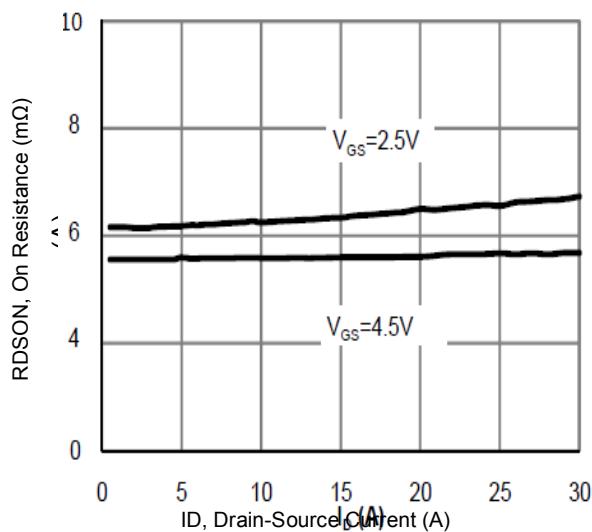


Fig3. On Resistance Vs. Gate-Source Voltage & Drain Current

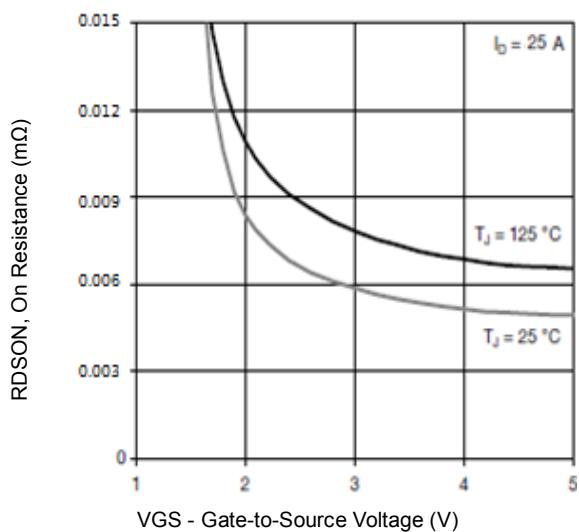


Fig4. Normalized On-Resistance Vs. Temperature

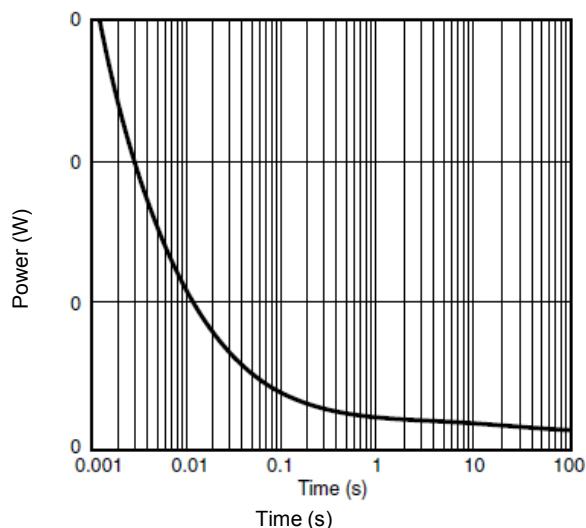


Fig5. Single Pulse Junction to Ambient

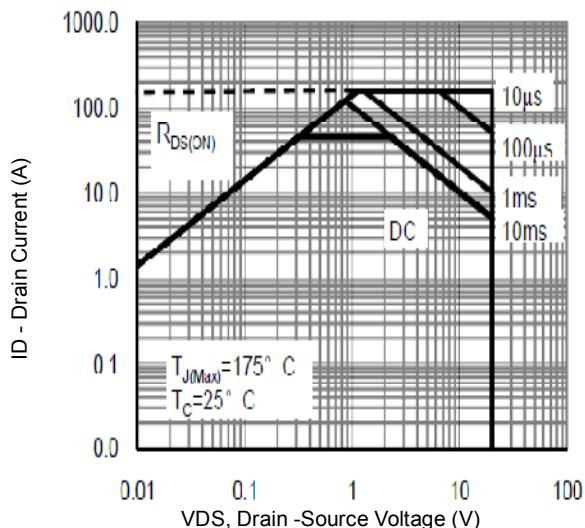


Fig6. Maximum Safe Operating Area

Typical Characteristics

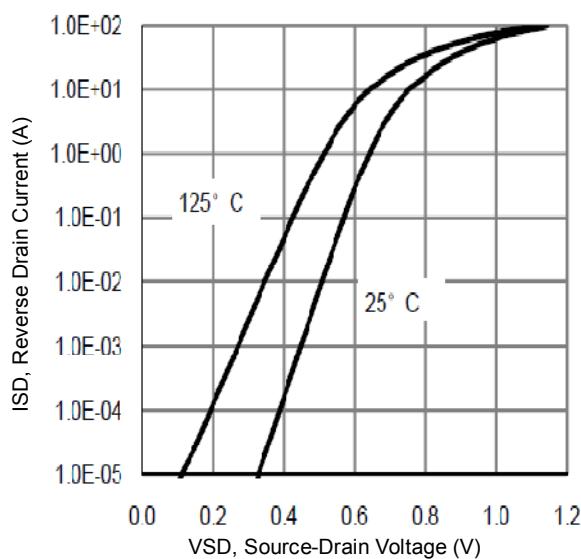


Fig7. Typical Source-Drain Diode Forward Voltage

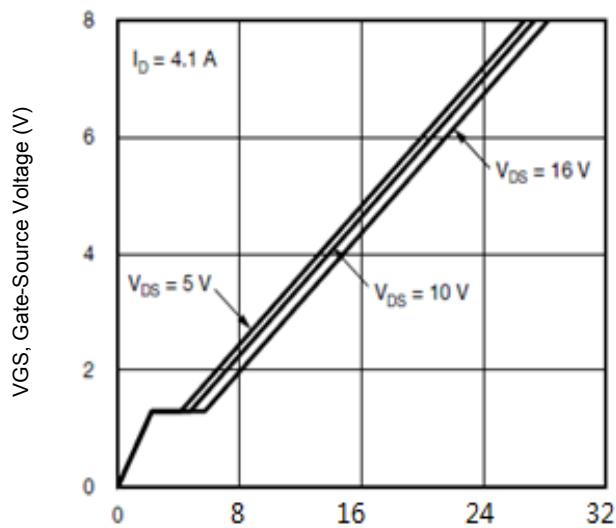


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

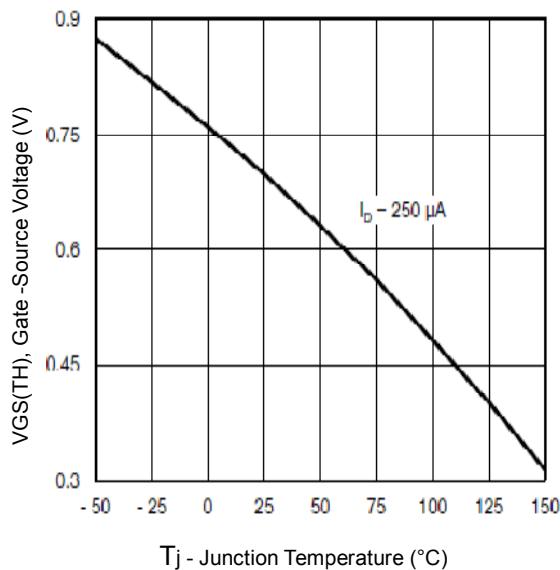


Fig9. Threshold Voltage Vs. Temperature

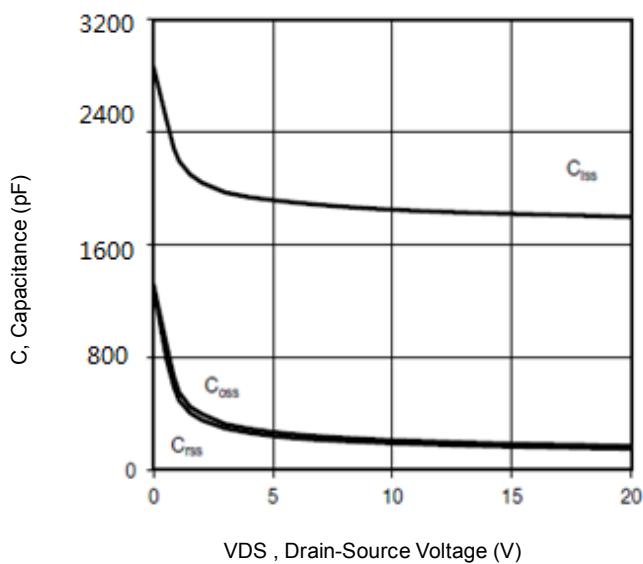


Fig10. Typical Capacitance Vs.Drain-Source Voltage

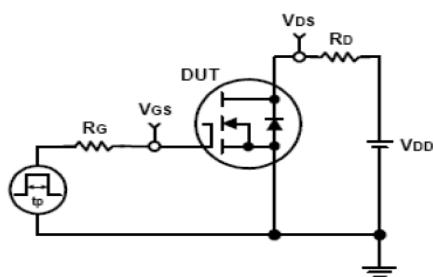


Fig11. Switching Time Test Circuit and waveforms

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